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Takashi Kondo

12.23-04

Execution Date(s) December 22, 2004

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

9. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Government Interest Assignment
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☐ Other

2. Name and address of receiving party(ies)

Name: Samsung Electronics Co., Ltd.

Internal Address:

Street Address: 416, Maetan-dong, Yeongtong-gu

City: Suwon-si

State: Gyeonggi-do

Country: Republic of Korea Zip: 442-742

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application or patent number(s):

A. Patent Application No.(s)

☒ This document is being filed together with a new application.
B. Patent No.(s)Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Roylance, Abrams, Berdo & Goodman, L.L.P.

Internal Address: Suite 600

Street Address: 1300 19th Street, NW

City: Washington

State: D.C. Zip: 20036

Phone Number: (202) 659-9076

Fax Number: (202) 659-9344

Email Address:

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☒ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers
 Expiration Date
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 Authorized User Name John E. Holmes

9. Signature:

Signature

December 23, 2004

Date

Martin E. Miller

Name of Person Signing

Total number of pages including cover
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3

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A S S I G N M E N T

WHEREAS, I, Takashi Kondo, a citizen of the Japan, residing respectively at c/o Samsung Yokohama Research Institute, 2-7, Sagasawa-cho, Tsurumi-ku, Yokohama 230-0027, Japan, (hereinafter ASSIGNOR), have made a certain invention entitled **MULTI-BEAM SEMICONDUCTOR LASER** for which I am making application for Letters Patent of the United States, which application has been executed concurrently herewith; and

WHEREAS, Samsung Electronics Co., Ltd., a corporation duly organized under the laws of the Republic of Korea, located and doing business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyonggi-do, Korea (hereinafter ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the aforementioned invention and the aforementioned application and any and all United States Letters Patent to be obtained on said invention and/or application;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for good and valuable consideration paid to me by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, by these presents do hereby sell, assign, set over and transfer unto the said ASSIGNEE, its successors, legal representatives or assigns, the entire right, title and interest in and to the aforesaid invention in and for the United States; and in, to and under the aforesaid United States application and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be filed on said invention in the United States; and our right to file said foreign applications and claim priority under the provisions of any international treaty or convention; and any Letters Patent of the United States issued or granted on said invention and/or said applications;

AND I HEREBY authorize and request the U.S. Patent and Trademark Office or other issuing authority to issue any and all patents on said invention and/or said application to said ASSIGNEE as sole assignee;

AND I HEREBY covenant that I have the full right to convey the entire right, title and interest herein assigned and that I have not executed and will not execute any assignment or other instrument in conflict herewith;

AND I HEREBY further covenant and agree to communicate to said ASSIGNEE, or its legal representatives, successors or assigns, any facts relating to said invention, including evidence for interference purposes or other proceedings, whenever requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to do everything possible to aid the said ASSIGNEE, its successors, legal representatives or assigns to obtain and enforce proper patent protection on and for said invention in the United

ASSIGNMENT

States, and likewise I make these provisions binding upon our heirs, legal representatives and/or administrators.

I hereby grant the firm of Roylance, Abrams, Berdo & Goodman the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

IN WITNESS WHEREOF, I have hereunder set my hand and seal this 22 day of December, 2004.

Takashi Kondo
Takashi Kondo

Witness

ASSIGNMENT

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